

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

JORNÉ et al.

Serial No. 09/174,337

Filed: October 19, 1998

For: UNIFORM ELECTROPLATING OF
WAFERS

Examiner: VALENTINE, D

Art Unit: 1741

Attorney Docket: A-68779/JC

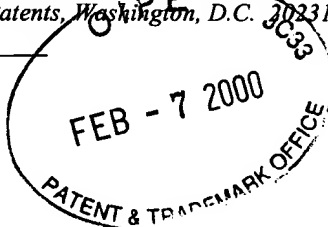
AMENDMENT

CERTIFICATE OF MAIL (37 CFR 1.8(A))

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as First Class Mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231 on February 1, 2000.

Claudia Galik
Claudia Galik

Assistant Commissioner for Patents
Washington, D.C. 20231



Sir:

Responsive to Office Action of October 8, 1999, please amend the above-entitled application as follows:

IN THE CLAIMS:

Cancel claims 1-18.

Add the following claims 19-38:

19. An electroplating device for the metallization of wafers for interconnection comprising an electroplating apparatus, a wafer coated with a thin barrier layer and a thin seed layer of the metal to be electroplated over said barrier layer, a mask around the circumferential edge of said wafer, a counter electrode, means for passing current between said counter electrode and said

A-68779/JC (1004251)

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